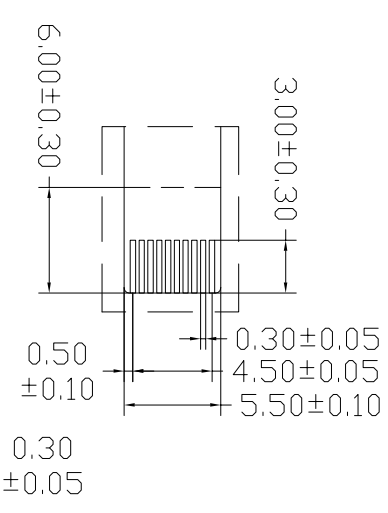


REV :	DESCRIPTION :	BY	DATE
A	RELEASED (BASE ON VERSION RT3)	Neil Zeng	2013/10/30
B	MODIFY THE SIZE OF TOP FPC	Neil Zeng	2013/11/06

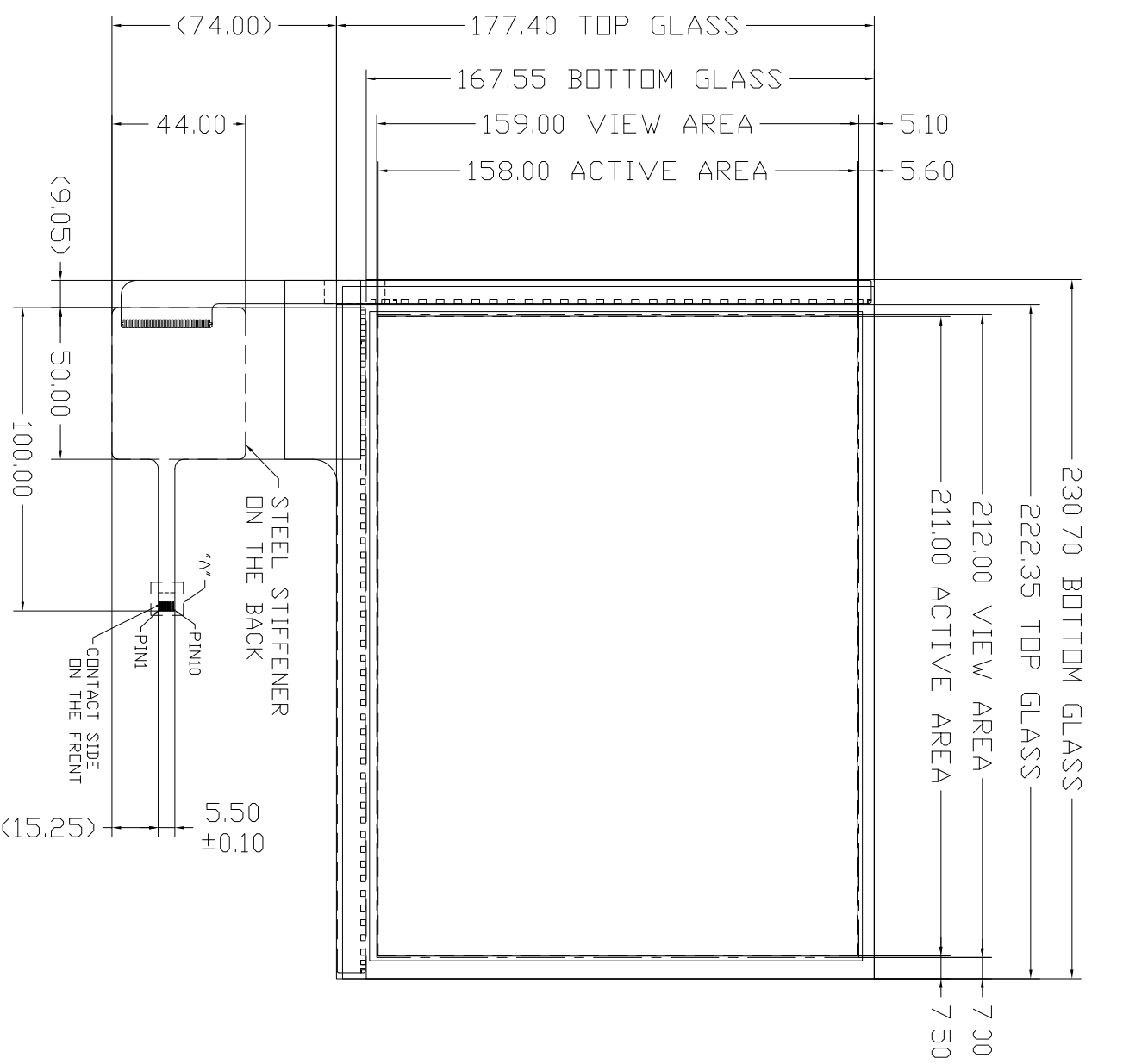
1.60±0.30
 (0.70) TOP GLASS (ITD FACE DOWN)
 (0.20) DCA
 (0.70) BOTTOM GLASS (ITD FACE UP)



DETAIL: "A"
SCALE: 5:1

PIN TABLE

PIN#	(I2C)	PIN#	(I2C)
1	SCL	6	GND
2	SDA	7	VDD (3.3V)
3	/RESET	8	NC
4	/CHG	9	NC
5	NC	10	NC



NOTES:

1. ALL DIMENSIONS IN MM.
2. OPERATING TEMPERATURE: -20°C TO 80°C
3. STORAGE TEMPERATURE: -30°C TO 80°C
4. FPC BENDING RADIUS IS R1.0MM MIN
5. ALL MATERIALS MUST BE ROHS COMPLIANT
6. (*) DIMENSION FOR REFERENCE
7. THE COMPATIBLE MOLEX FPC CONNECTOR IS 52745-1097 OR EQUIVALENT



UNLESS OTHERWISE NOTED :

UNITS	DECIMAL
INCHES [mm]	.XXX[.XX] ±0.008(0.20)
ANGLES	±0.5°



ENGR MANAGER :

CHECKED BY : Jacky Li DATE : 2013/11/06

DWN BY : Neil Zeng DATE : 2013/11/06

DRAWING TITLE : F104-1188S-194 TP

DRAWING No. : F104-1188S-194

SCALE 1 : 1 SHEET : 1 OF 1

REV : B